

Self-leveling, withstands high humidity environments

5108 is a one part, black, electrically isolating, precision mixed, degassed, and frozen epoxy compound specifically designed for potting and sealing electronic components. 5108 is a self leveling material that exhibits low shrinkage once cured and can withstand high temperatures and high humidity or wet environments. This material is also environmentally friendly and considered non-hazardous per D.O.T. regulations.

UNCURED	
Pot Life @ 25°C	2 hours
Viscosity @ 25°C	5,000 cPs
Shelf Life @ -40°C	6 months
CURE OPTIONS	1 hour @ 92°C 4 hours @ 65°C 48 hours @ 25°C
CURED PROPERTIES	Based on cure of 4 hours @ 65°C
Color	Black
Shore D Hardness	80
Density (g/cc)	1.07
Glass Transition Temp (°C)	45
Shrinkage Linear (%)	0.26
ELECTRICAL PROPERTIES	Based on cure of 4 hours @ 65°C
Dielectric Constant	3.2 @ 1 kHz
Dissipation Factor	0.008 @ 1 kHz
Volume Resistivity (ohm-cm)	7.0E 13 @ 500 VDC
THERMAL PROPERTIES	Based on cure of 4 hours @ 65°C
Glass Transition Temp (°C)	45
Degradation Temp. (°C)	275
OUTGASSING PROPERTIES	Based on cure of 4 hours @ 65°C
TML (%)	0.75
CVCM (%)	0.01
WVR (%)	0.39
ACOUSTIC PROPERTIES	
Velocity (m/s)	2,345
Impedance (MRayles)	2.51
Loss (dB/cm-MHz)	-4.83
Density (g/cc)	1.07

KEY FEATURES

Adheres to Dissimilar Materials

Self Leveling

Hydrolytic Stability

High Temperature Resistant

Low Shrinkage

Non-hazardous per D.O.T. Regulations

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Rev E

3/1/2022